

ABSTRACT OF THE DISCLOSURE

An electronic module includes an EL section; a first substrate on which the EL section is formed; a second substrate attached to the first substrate; an integrated circuit
5 chip mounted on the second substrate; a plurality of first power supply interconnects formed on the first substrate, extending through a pair of regions located on both sides of the EL section; and a plurality of second power supply interconnects formed on the second substrate, extending through a pair of regions located on both sides of the integrated circuit chip.